SAMSUNG
ELECTRO-MECHANICS

Ver 201305

Chip Bead For EMI Suppression

CIB32/41 Series (3225/4516 / EIA 1210/1806)

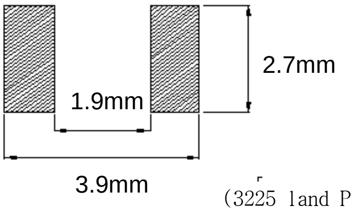
APPLICATION

High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

FEATURES

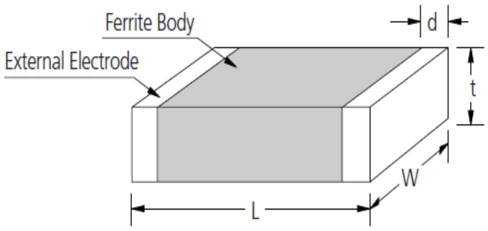
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.

RECOMMENDED LAND PATTERN



(3225 land Pattern)

DIMENSION



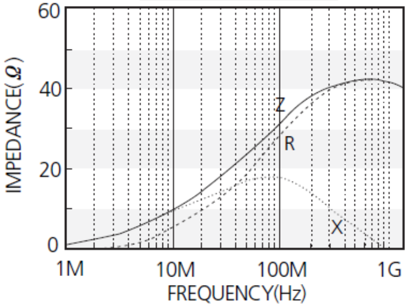
Type	**Dimension [mm]**			
	L	**W**	**t**	**d**
32	3.2±0.2	2.5±0.2	1.3±0.2	0.5+0.3 -0.3
41	4.5±0.2	1.6±0.2	1.6±0.2	0.5+0.3 -0.3

DESCRIPTION

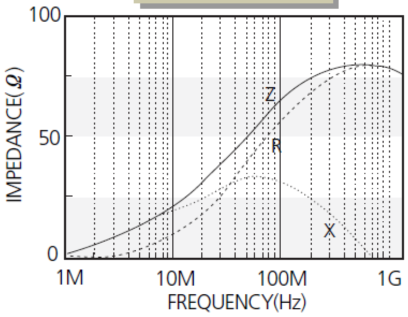
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB32P310	1.3±0.2	31	0.02	3000
CIB32P600	1.3±0.2	60	0.02	1500
CIB41P800	1.6±0.2	80	0.03	1000
CIB41P151	1.6±0.2	150	0.05	1000

CHARACTERISTIC DATA

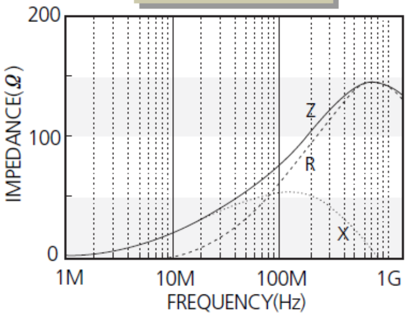
CIB32P310



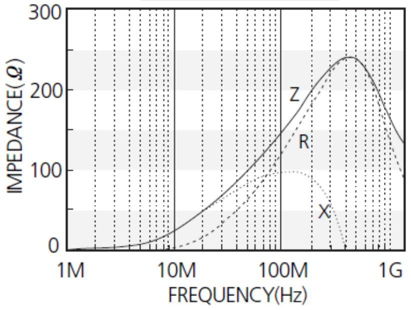
CIB32P600



CIB41P800



CIB41P151



PRODUCT IDENTIFICATION

CI	B	32	P	310	N	E
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Chip Beads

(2) M: Multi-layer type B:Mono-layer type

(3) Dimension

(4) Material Code

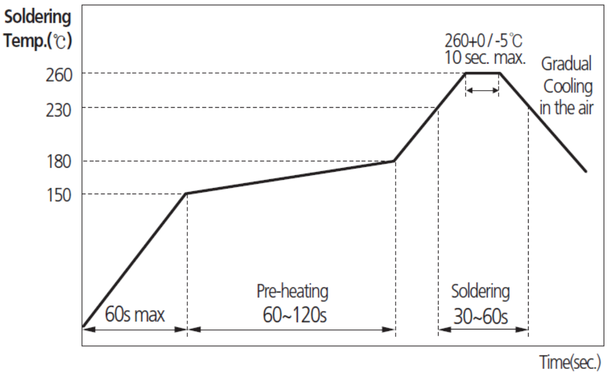
(5) Nominal impedance (310:31Ω)

(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)

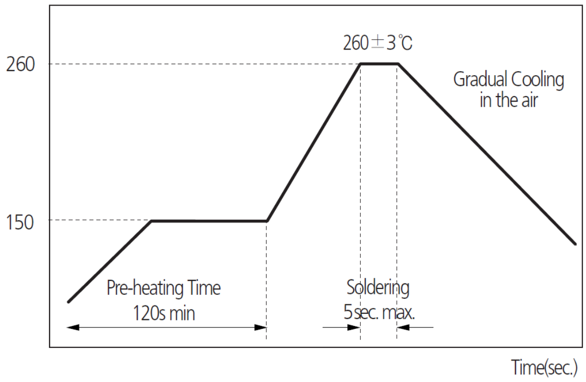
(7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Size	Packaging Style	Quantity(pcs/reel)
3225	Embossed Taping	2,500
4516	Embossed Taping	2,000